

CLAIMS

1. A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:
wetting undried said metal particles having been water washed, and
applying collision force to a slurry including at least said wetted metal particles and said ceramics particles.
2. A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:
wetting undried said metal particles having been water washed, and
10 colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along relatively different direction from the first slurry.
3. The manufacturing process of conductive composition as in claim 2, wherein
said first slurry and said second slurry have substantially the same
composition.
4. The manufacturing process of conductive composition as in claim 1, wherein an
average particle size of said ceramics particles is less than that of said metal
particles.
5. The manufacturing process of conductive composition as in claim 2, wherein an
average particle size of said ceramics particles is less than that of said metal
particles.
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6. The manufacturing process of conductive composition as in claim 1, wherein an
average particle size of said ceramics particles is a half of or less than an
average particle size of said metal particles.
7. The manufacturing process of conductive composition as in claim 2, wherein an

average particle size of said ceramics particles is a half of or less than an average particle size of said metal particles.

8. The manufacturing process of conductive composition as in claim 1, wherein an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles.

9. The manufacturing process of conductive composition as in claim 2, wherein an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles.

10. The manufacturing process of conductive composition as in claim 1, wherein an average particle size of said metal particles is $0.5 \mu m$ or less.

11. The manufacturing process of conductive composition as in claim 2, wherein an average particle size of said metal particles is $0.5 \mu m$ or less.

12. The manufacturing process of conductive composition as in claim 4, wherein an average particle size of said metal particles is $0.5 \mu m$ or less.

13. The manufacturing process of conductive composition as in claim 5, wherein an average particle size of said metal particles is $0.5 \mu m$ or less.

14. The manufacturing process of conductive composition as in claim 1, wherein said metal particles are Ni or Ni content compound.

15. The manufacturing process of conductive composition as in claim 2, wherein said metal particles are Ni or Ni content compound.

16. The manufacturing process of conductive composition as in claim 1, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

17. The manufacturing process of conductive composition as in claim 2, wherein said conductive composition is a conductive paste to form an electrode on

ceramic dielectric substrate.

18. The conductive paste comprising conductive composition manufactured by the process as in claim 1.
19. The conductive paste comprising conductive composition manufactured by the process as in claim 2.
20. A multilayer electronic component manufactured by using the conductive paste as in claim 18.
21. A multilayer electronic component manufactured by using the conductive paste as in claim 19.

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